

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Nir Sela</td> <td>06/27/2012</td> </tr> <tr> <td>Adi Hirschstein</td> <td>06/27/2012</td> </tr> <tr> <td>Ron Bigman</td> <td>06/27/2012</td> </tr> <tr> <td>Shay Zukerman</td> <td>06/28/2012</td> </tr> </tbody> </table>		Name	Execution Date	Nir Sela	06/27/2012	Adi Hirschstein	06/27/2012	Ron Bigman	06/27/2012	Shay Zukerman	06/28/2012
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RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>Bretford Manufacturing, Inc.</td> </tr> <tr> <td>Street Address:</td> <td>11000 Seymour Avenue</td> </tr> <tr> <td>City:</td> <td>Franklin Park</td> </tr> <tr> <td>State/Country:</td> <td>ILLINOIS</td> </tr> <tr> <td>Postal Code:</td> <td>60131</td> </tr> </table>		Name:	Bretford Manufacturing, Inc.	Street Address:	11000 Seymour Avenue	City:	Franklin Park	State/Country:	ILLINOIS	Postal Code:	60131
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<table border="1"> <tr> <td>Name:</td> <td>EMC Corporation</td> </tr> <tr> <td>Street Address:</td> <td>176 South Street</td> </tr> <tr> <td>City:</td> <td>Hopkinton</td> </tr> <tr> <td>State/Country:</td> <td>MASSACHUSETTS</td> </tr> <tr> <td>Postal Code:</td> <td>01748</td> </tr> </table>		Name:	EMC Corporation	Street Address:	176 South Street	City:	Hopkinton	State/Country:	MASSACHUSETTS	Postal Code:	01748
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PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13539176</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13539176						
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Application Number:	13539176										
CORRESPONDENCE DATA											
Fax Number:	9782649119										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone:	978-371-3218										
Email:	john@gorecki.us										
Correspondent Name:	John C Gorecki										
Address Line 1:	P.O. Box 553										

OP \$40.00 13539176

Address Line 4: Carlisle, MASSACHUSETTS 01741

NAME OF SUBMITTER:

John C. Gorecki, Reg. No. 38471

Total Attachments: 6

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ASSIGNMENT

WHEREAS, I, Nir Sela, Adi Hirschtein, Ron Bigman, and Shay Zukerman, have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled

METHOD AND APPARATUS FOR IDENTIFYING DATABASE I/O ACTIVITY

, which:

☒ is being executed on even date herewith and is about to be filed in the United States Patent Office;

☐ was filed on _____ as U.S. Application No. _____;

☐ was patented under U.S. Patent No. _____ on _____.

WHEREAS, EMC Corporation (hereinafter "ASSIGNEE"), a corporation organized and existing under the laws of the Commonwealth of Massachusetts and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748, desires to acquire an interest therein in accordance with agreements duly entered into with me;


NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, I have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by me had this assignment and sale not been made; I hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. I hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

AND, I hereby further agree for me and my executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution, reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, I do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives.

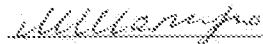
IN TESTIMONY WHEREOF, I have hereunto set my hand and affixed my seal as set forth below:

Date: 22/06/2012


Inventor's Signature

Print full name of inventor: Nir Sela
Residence: 18 Dror, Tzur Igal 44862, Israel
Citizenship: Israel
Mailing Address: 18 Dror, Tzur Igal 44862, Israel

I Marina Shapiro (name) whose residential address is
Ha-Yovel 31/1 Raanana
was personally present and did see Nir Sela, who is personally known to me, execute the above assignment.

 (signature of first witness)

Signed at Ha-Mada 7, Herzlia (location of witness signature)

on this day 06/28/2012 of 2012. (date of signature)

I Julia Yakovlev (name) whose residential address is
Sivan 17/6, Modi'in
was personally present and did see Nir Sela, who is personally known to me, execute the above assignment.

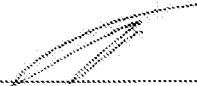
 (signature of second witness)

Signed at Ha-Mada 7, Herzlia (location of witness signature)

on this day 06/28 of 2012. (date of signature)

Date:

27/06/12


Inventor's Signature

Print full name of inventor:

Adi Hirshtein

Residence:

19 Borochoy, Givataim 53204, Israel

Citizenship:

Israel

Mailing Address:

19 Borochoy, Givataim 53204, Israel

I Marina Shapiro (name) whose residential address is

Ha-Yovel 31/1, Ramat

was personally present and did see Adi Hirshtein, who is personally known to me, execute the above assignment.

William (signature of first witness)

Signed at Ha-Mada 7, Herzlia (location of witness signature)

on this day 06/28 of 2012. (date of signature)

I Julia Yakovlev (name) whose residential address is

Sivan 17/6, Modiin

was personally present and did see Adi Hirshtein, who is personally known to me, execute the above assignment.


(signature of second witness)

Signed at HaMada 7, Herzlia (location of witness signature)

on this day 06/28 of 2012. (date of signature)

Date: 27.6.2012

[Signature]
Inventor's Signature

Print full name of inventor: **Ron Bigman**
Residence: 17 Harav Kapach, Holon 58248, Israel
Citizenship: Israel
Mailing Address: 17 Harav Kapach, Holon 58248, Israel

I Maring Shapiro (name) whose residential address is
Ha-Mada 7 Ha Yovel 311 Ramat
was personally present and did see Ron Bigman, who is personally known to me, execute the
above assignment.

[Signature] (signature of first witness)

Signed at Ha-Mada 7, Herzlia (location of witness signature)

on this day 06/28 of 2012. (date of signature)

I Julia Yakovlev (name) whose residential address is
Sivan, 14/6, Modiin
was personally present and did see Ron Bigman, who is personally known to me, execute the
above assignment.


[Signature] (signature of second witness)

Signed at HaMada 4, Herzlia (location of witness signature)

on this day 06/28 of 2012. (date of signature)

Date:

28/6/12


Inventor's Signature

Print full name of inventor:

Shay Zukerman

Residence:

16 Hagan Eliyau St., Ramat Gan 52364, Israel

Citizenship:

Israel

Mailing Address:

16 Hagan Eliyau St., Ramat Gan 52364, Israel

I Marina Shapiro (name) whose residential address is

Ha Yovel 311, Roshana
was personally present and did see Shay Zukerman, who is personally known to me, execute the above assignment.

Marina Shapiro (signature of first witness)

Signed at Ha-Mada 7 Harelia (location of witness signature)

on this day 06/28 of 2012. (date of signature)

I Julia Yakovlev (name) whose residential address is

Sivan 17/6, Modin
was personally present and did see Shay Zukerman, who is personally known to me, execute the above assignment.


(signature of second witness)

Signed at Ha-Mada 7 Harelia (location of witness signature)

on this day 06/28 of 2012. (date of signature)